

SLOT HOLES: TOP TO BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	FINISHED SIZE	ROTATION	PLATED	QTY
	787.4x43.3	90.000	NON-PLATED	4

DRILL CHART: TOP to BOTTOM					
ALL UNITS ARE IN MILS					
FIGURE	FINISHED SIZE	ROTATION	PLATED	PLATED	QTY
A	12.0	-	PLATED	546	
B	31.5	-	PLATED	16	
C	35.43	-	PLATED	34	
D	43.31	-	PLATED	6	
E	47.24	-	PLATED	8	
F	51.0	-	PLATED	2	
G	55.0	-	PLATED	5	
H	59.05	-	PLATED	4	
I	82.68	-	PLATED	2	
L	35.43	-	NON-PLATED	6	
M	125.98	-	NON-PLATED	2	

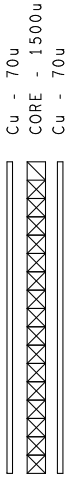
Finished Hole Tolerance - All units are in Inches -			
Finish Hole Diameter	Plated Through Finish Hole Diameter	Non Plated Through Finish Hole Diameter	
0.008"-0.013"	+0.002/-FHS*	+/-0.002"	
0.014"-0.063"	+/-0.003"	+/-0.002"	
0.064"-0.156"	+/-0.004"	+/-0.003"	
0.157"-0.250"	+/-0.007"	+/-0.004"	
0.251" and up	+/-0.007"	+/-0.005"	
0.125"	Non Plated Only	+0.003/-0.000"	

FABRICATION NOTE: \_\_\_\_\_

- 1-FABRICATE USING LATEST REVISION OF IPC-6012A CLASS 2 OR ABOVE
- 2-FABRICATE USING MASTER WORKP. E5V91N3P260251 R1. FOR CIRCUIT PATTERN NO DEVIATION FROM MASTER WORKP. ARE PERMITTED WITHOUT WRITTEN APPROVAL FROM AN AUTHORIZED SMT/circuitronics REPRESENTATIVE
- 3-VENDOR MUST BE UL QUALIFIED AND BOARDS MUST BE IDENTIFIED WITH APPROPRIATE VENDOR UL IDENTIFICATION MARK. LOT OR JOB NUMBER AND PCB MATERIAL FLAMMABILITY RATING (94V-0) MINIMUM
- 4-MATERIAL: FR4 R6HS COMPLIANT MINIMUM 170 C (HIGH TG)  
SEE "DETAIL "A"" FOR BOARD THICKNESS, COPPER WEIGHT AND LAYER CONSTRUCTION
- 5-GRENE SOLDER MASK BOTH SIDE OF BOARD WITH LIQUID PHOTO IMAGEABLE SOLDERMASK
- 6-FINISH: HAL Lead Free
- 7-FOR SMT COMPONENTS WITH PIN PITCH OF 0.019 INCH OR MORE NO GANG RELIEF OF SOLDER MASK IS ALLOWED
- 8-SILKSREEN TO BE WHITE, NON CONDUCTIVE, EPOXY INK OR EQUIVALENT
- 9-THIS IS NOT A CONTROLLED IMPEDANCE BOARD
- 10-ON BOTTOM PCB MUST BE IDENTIFIED MANUFACTURER LOGO AND PCB TYPE (MEANS OF MATERIAL TYPE INDICATED ON THE YELLOW CARD DOCUMENT)
- 11-VENDOR TO PROVIDE BOARD STACK-UP FOR IMPEDANCE APPROVAL PRIOR TO BOARD FABRICATION STACK UP AND IMPEDANCE TO INCLUDE COPPER PLATING ON OUTER LAYERS HAL DRAWING STACK-UP DIMENSION ARE PROVIDED FOR REFERENCE ONLY
- 12-VENDOR TO PROVIDE BOARD FOR IMPEDANCE TEST RESULTS AND COUPON
- 13-TERDROPPING OF VIAS AND PADS ALLOWED AT PAD TO TRACE INTERSECTION TO INSURE A 2MIL ANULAR RING AT THE JUNCTION
- 14-REMOVE SILKSREEN FROM SOLDERABLE SURFACE
- 15-ALL BOARD TO BE 100% ELECTRICALLY NETLIST TESTED FOR OPENS AND ON SHORTS. APPLY TEST STAMP IN REFERENCED AREA
- 16-THIS BOARD SHALL BE FULLY COMPLIANT WITH UL796

## DETAIL "A"

LAYER BUILD UP  
(reference only)



(external Cu th are after plating)  
(estimated total thickness 1650u

[illegible]